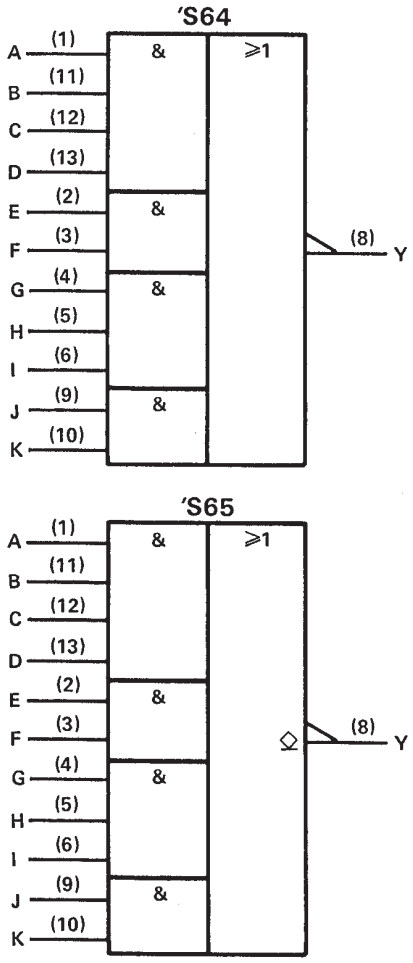
- **Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs**
- **Dependable Texas Instruments Quality and Reliability**

description

These devices contain 4-2-3-2 input AND-OR-INVERT gates. They perform the Boolean function $Y = \overline{ABCD + EF + GHI + JK}$. The 'S64 has totem-pole outputs and the 'S65 has open-collector outputs.

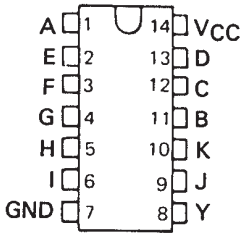
The SN54S64 and the SN54S65 are characterized for operation over the full military temperature range of −55°C to 125°C. The SN74S64 and the SN74S65 are characterized for operation from 0°C to 70°C.

logic symbols†

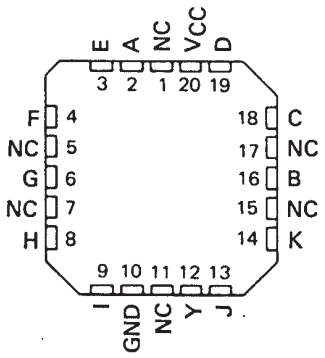


†These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

SN54S64, SN54S65 . . . J OR W PACKAGE
SN74S64, SN74S65 . . . D OR N PACKAGE
(TOP VIEW)

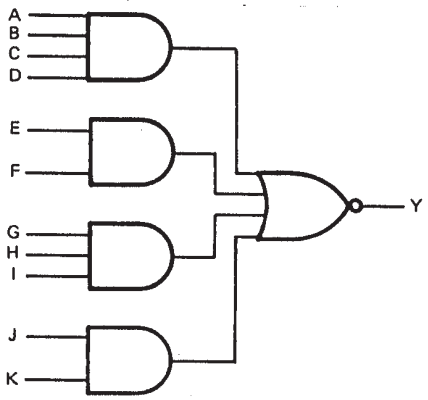


SN54S64, SN54S65 . . . FK PACKAGE
(TOP VIEW)



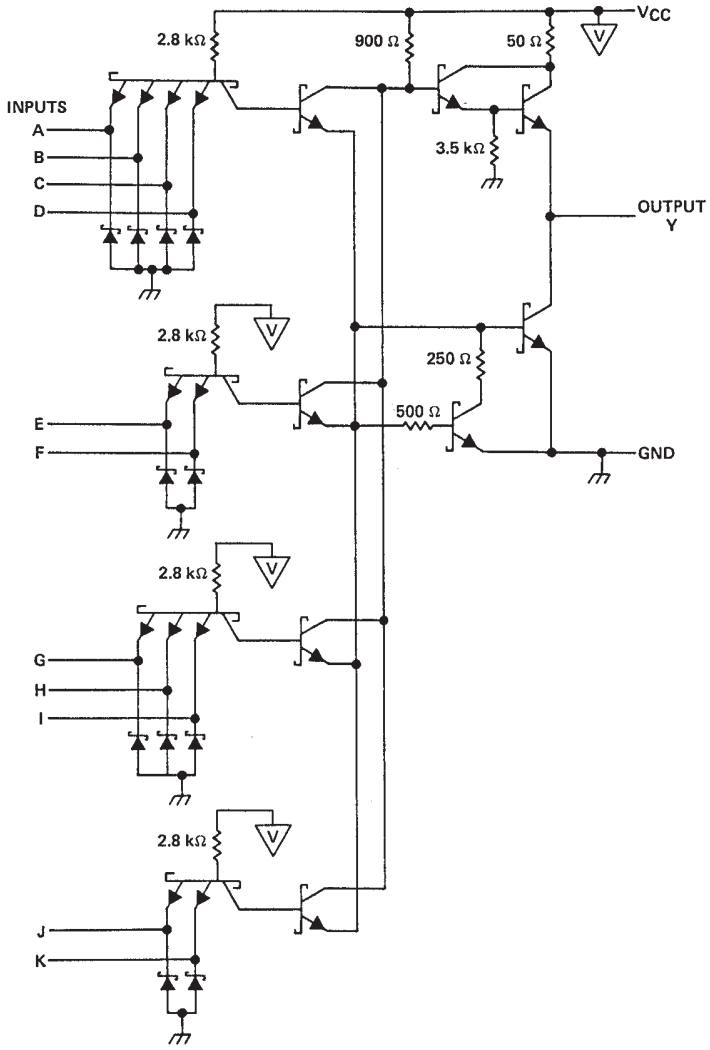
NC – No internal connection

logic diagram (each device) (positive logic)

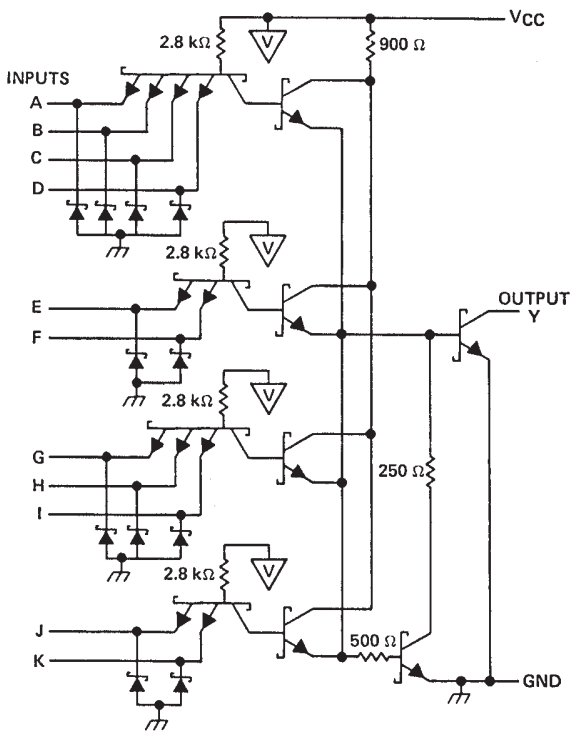


schematics (each gate)

'S64



'S65



Resistor values shown are nominal and in ohms.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage . . . . . 5.5 V
Off-state output voltage, 'S65 . . . . . 7 V
Operating free-air temperature range: SN54' . . . . . −55°C to 125°C
SN74' . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

recommended operating conditions

		SN54S64			SN74S64			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I_{OH}	High-level output current			−1			−1	mA
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS †			SN54S64			SN74S64			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN,	I_I = −18 mA				−1.2			−1.2	V
V_{OH}	V_{CC} = MIN,	V_{IL} = 0.8 V,	I_{OH} = −1 mA	2.5	3.4		2.7	3.4		V
V_{OL}	V_{CC} = MIN,	V_{IH} = 2 V,	I_{OL} = 20 mA			0.5			0.5	V
I_I	V_{CC} = MAX,	V_I = 5.5 V				1			1	mA
I_{IH}	V_{CC} = MAX,	V_I = 2.7 V				50			50	μA
I_{IL}	V_{CC} = MAX,	V_I = 0.5 V				−2			−2	mA
I_{OS}§	V_{CC} = MAX			−40		−100	−40		−100	mA
I_{CCH}	V_{CC} = MAX,	V_I = 0			7	12.5		7	12.5	mA
I_{CCL}	V_{CC} = MAX,	V_I = 4.5 V			8.5	16		8.5	16	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Any	Y	R_L = 280 Ω,	C_L = 15 pF		3.5	5.5	ns
t_{PHL}						3.5	5.5	ns
t_{PLH}			R_L = 280 Ω,	C_L = 50 pF		5		ns
t_{PHL}						5.5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

recommended operating conditions

		SN54S65			SN74S65			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
V_{OH}	High-level output voltage			5.5			5.5	V
I_{OL}	Low-level output current			20			20	mA
T_A	Operating free-air temperature	−55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	SN54S65			SN74S65			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	V_{CC} = MIN, I_I = −18 mA			1.2			1.2	V
I_{OH}	V_{CC} = MIN, V_{IL} = 0.8 V, V_{OH} = 5.5 V						0.25	mA
	V_{CC} = MIN, V_{IL} = 0.7 V, V_{OH} = 5.5 V			0.25				
V_{OL}	V_{CC} = MIN, V_{IH} = 2 V, I_{OL} = 20 mA		0.2	0.4		0.2	0.4	V
I_I	V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	V_{CC} = MAX, V_I = 2.7 V			50			50	μA
I_{IL}	V_{CC} = MAX, V_I = 0.5 V			−2			−2	mA
I_{CCH}	V_{CC} = MAX, V_I = 0		6	11		6	11	mA
I_{CCL}	V_{CC} = MAX, V_I = 4.5 V		8.5	16		8.5	16	mA

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{PLH}	Any	Y	R_L = 280 Ω, C_L = 15 pF	2	5	7.5	ns
t_{PHL}				2	5.5	8.5	ns
t_{PLH}			R_L = 280 Ω, C_L = 50 pF		8		ns
t_{PHL}					6.5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07402BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07402BCA	Samples
JM38510/07402BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07402BDA	Samples
M38510/07402BCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07402BCA	Samples
M38510/07402BDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07402BDA	Samples
SN54S64J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S64J	Samples
SNJ54S64J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S64J	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

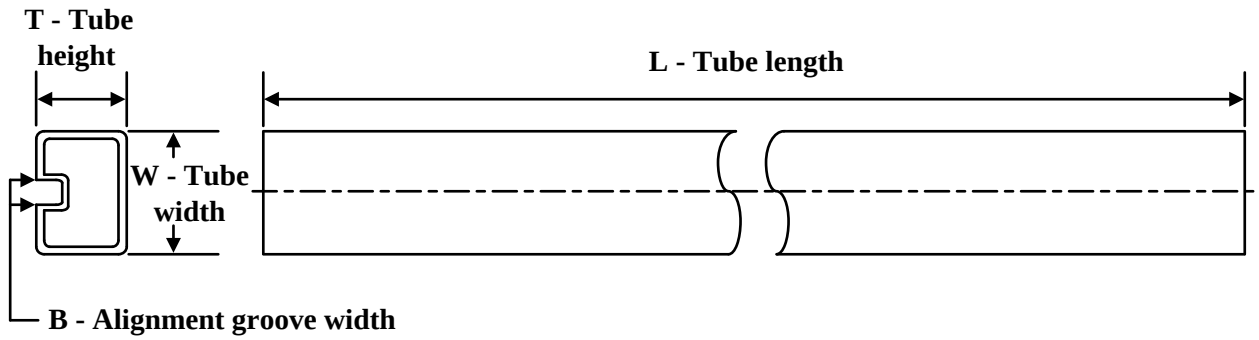
(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TUBE



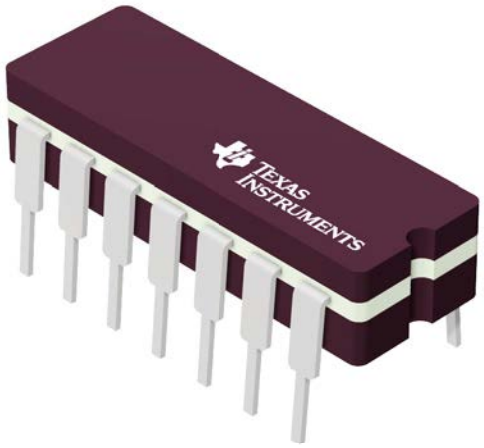
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/07402BDA	W	CFP	14	25	506.98	26.16	6220	NA
M38510/07402BDA	W	CFP	14	25	506.98	26.16	6220	NA

GENERIC PACKAGE VIEW

J 14 CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

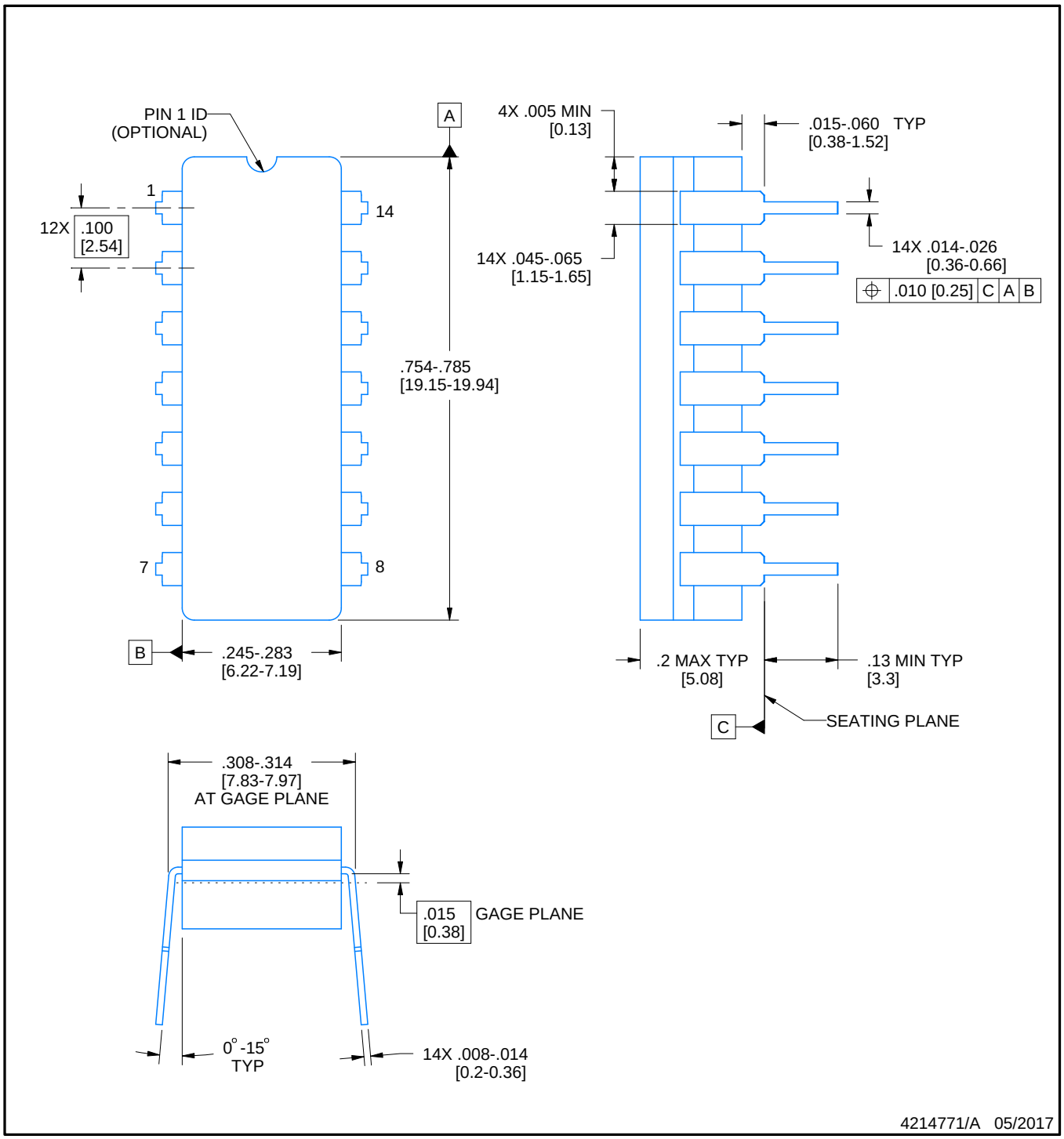
4040083-5/G

PACKAGE OUTLINE

J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

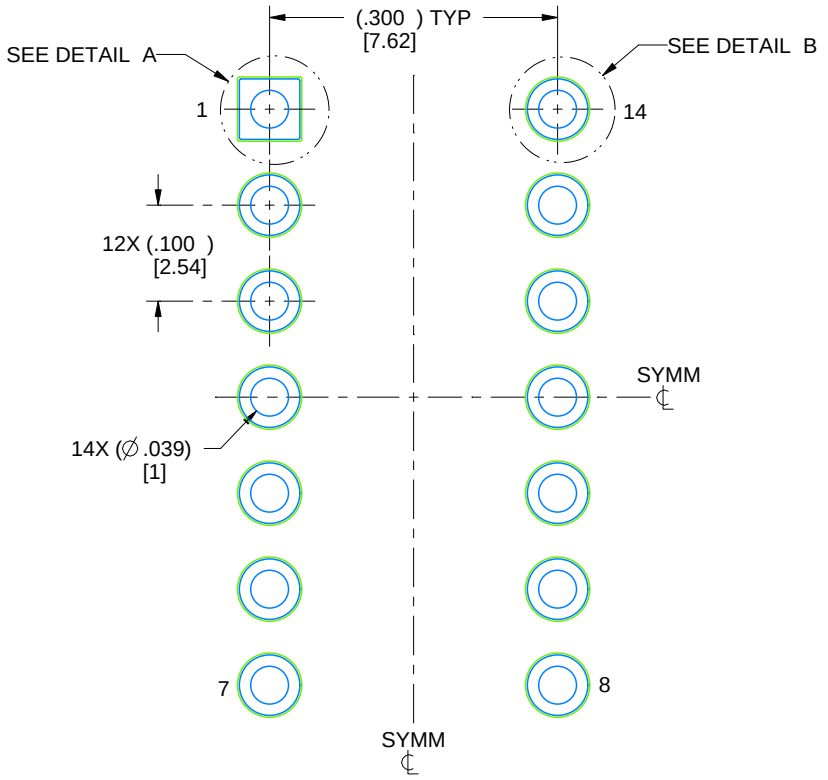
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermitically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

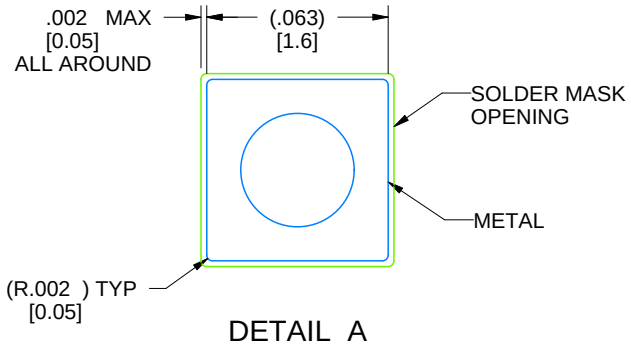
J0014A

CDIP - 5.08 mm max height

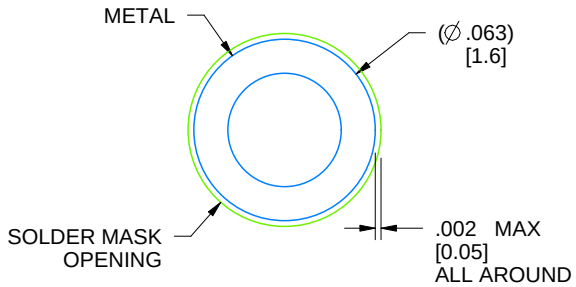
CERAMIC DUAL IN LINE PACKAGE



LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



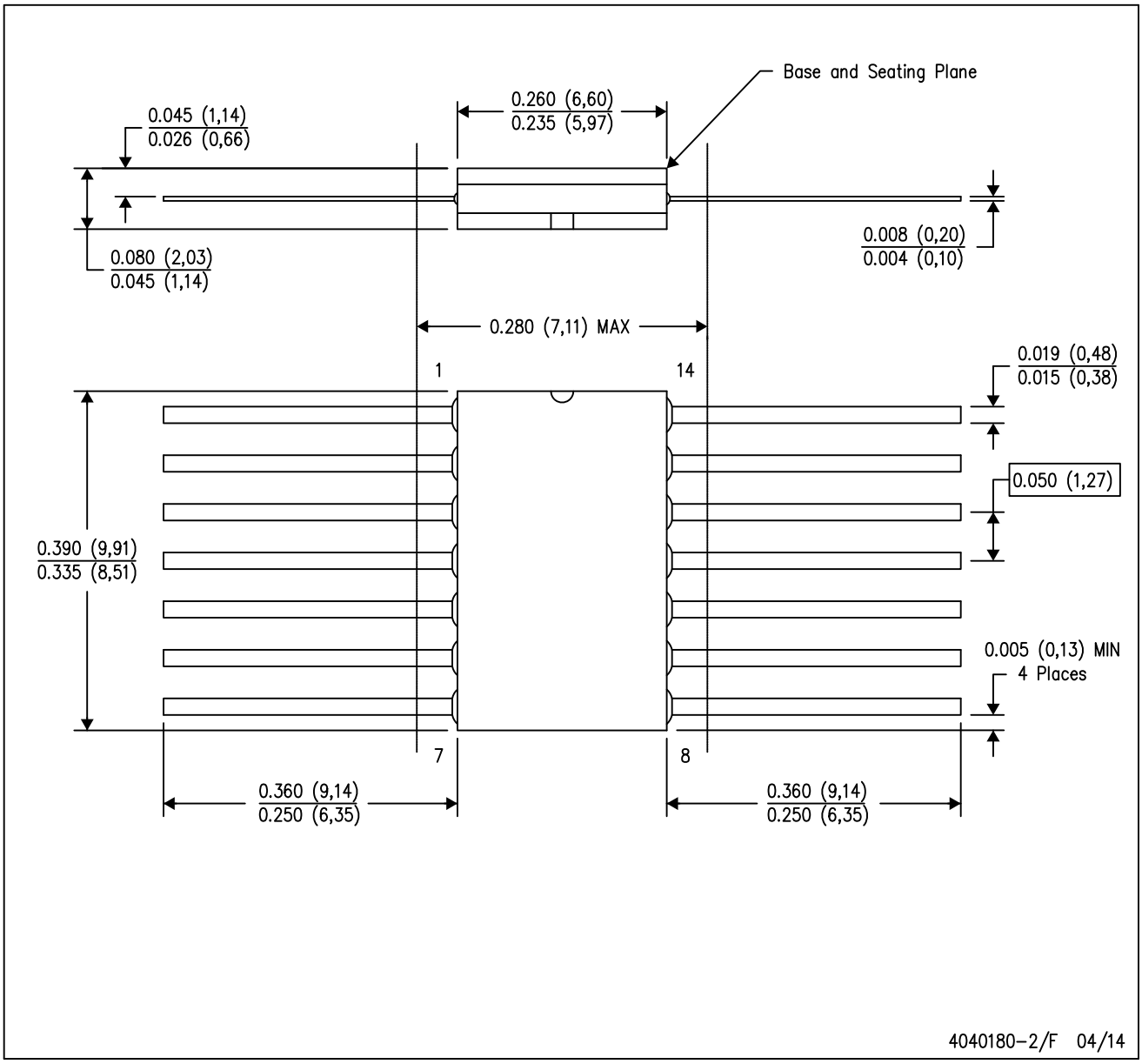
DETAIL A
SCALE: 15X



DETAIL B
13X, SCALE: 15X

4214771/A 05/2017

W (R–GDFP–F14) CERAMIC DUAL FLATPACK



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F14

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